

Xencor™ HPPA LGF-4060

high performance polyamide

Xencor™ HPPA LGF-4060 is a 60% Long Glass Fiber reinforced, easy-flowing, heat stabilized HPPA with a very high flexural modulus. It exhibits unique stiffness/toughness combination, an excellent retention of properties in a wide temperature range, as well as outstanding creep and fatigue resistance.

Xencor™ HPPA LGF-4060 has a pellet length of 9mm and can be processed on most injection-molding machines. It is available in black.

Black: Xencor™ HPPA LGF-4060 BK 000-9

General

 Commercial: Active 		
Africa & Middle EastAsia PacificEurope	 Latin America North America	
Long Glass Fiber, 60% Filler by Weight		
 Creep Resistant Electrically Insulating Fatigue Resistant High Impact Resistance High Temperature Stiffness 	 Hot Water Moldability Low CLTE Low Shrinkage Low Warpage	
 Aircraft Applications Automotive Applications	Consumer ApplicationIndustrial Applications	
RoHS Compliant		
• Black		
• Pellets		
Compression MoldingInjection Molding	Overmolding	
Dry	Conditioned Unit	Test method
1.69	g/cm³	ISO 1183
0.10	%	Internal Method
1.2	%	ISO 62
	Africa & Middle East Asia Pacific Europe Long Glass Fiber, 60% Filler by Creep Resistant Electrically Insulating Fatigue Resistant High Impact Resistance High Temperature Stiffness Aircraft Applications Automotive Applications ROHS Compliant Black Pellets Compression Molding Injection Molding Dry 1.69 0.10	 Africa & Middle East Asia Pacific Europe Long Glass Fiber, 60% Filler by Weight Creep Resistant Electrically Insulating Fatigue Resistant High Impact Resistance High Temperature Stiffness Aircraft Applications Automotive Applications RoHS Compliant Black Pellets Compression Molding Injection Molding Overmolding

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Mechanical	Dry	Conditioned Unit	Test method	
Tensile Modulus				
23°C	22500	MPa	ISO 527-1	
23°C		21000 MPa	ISO 527-2	
70°C	17000	MPa	ISO 527-1	
Tensile Stress			ISO 527-2	
Break, 23°C	285	250 MPa		
Break, 70°C	200	MPa		
Tensile Strain (Break)	2.0	2.0 %	ISO 527-2	
Flexural Modulus (23°C)	21500	MPa	ISO 178	
Flexural Stress (23°C)	420	MPa	ISO 178	
Impact	Dry	Conditioned Unit	Test method	
Charpy Notched Impact Strength	,		ISO 179	
-30°C	60	kJ/m²	2	
23°C	60	60 kJ/m²		
Charpy Unnotched Impact Strength		•	ISO 179	
-30°C	100	kJ/m²		
23°C	110	100 kJ/m²		
		•		
Thermal	Dry	Conditioned Unit	Test method	
Deflection Temperature Under Load				
0.45 MPa, Unannealed	260	°C	ISO 75-2/B	
1.8 MPa, Unannealed	255	°C	ISO 75-2/A	
CLTE - Flow	1.8E-5	cm/c		
Thermal Conductivity	0.35	W/m/	K ISO 22007	
Electrical	Dry	Conditioned Unit	Test method	
Electric Strength (2.00 mm)	35	kV/m		
Comparative Tracking Index	600	V	IEC 60112	
Surface Resistivity	1.0E+13	ohms		
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Additional Information			20.1110	
Conditioned • Conditioned c	lata generated acco	ording to test method IS	SO 1110	
Injection		Dry Unit		
Drying Temperature		80 °C		
Drying Time	4.0 to 8.0 hr			
Suggested Max Moisture	0.10 %			
Suggested Max Regrind	20 %			
Rear Temperature	290 to 300 °C			
Middle Temperature	300 °C			
Front Temperature	300 °C			
Nozzle Temperature	300 °C			
Processing (Melt) Temp	< 320 °C			
Mold Temperature	80 to 120 °C			
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Injection Notes

Pre-Drying -- Since polyamides are hygroscopic materials as well as sensitive to moisture during processing, this product should always be pre-dried.

Regrind -- Regrind of highly filled thermoplastic materials, such as this material, should only be recycled with special care. The regrind content must never exceed 20% and only regrind of optimum quality should be used. In any case, part properties should be checked.

Notes

Typical properties: these are not to be construed as specifications.

¹ Tested in accordance with S.O.P. methods

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